

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2616	257/723.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:47
L2	78	L1 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:47
L3	2561	257/787.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:50
L4	43	L3 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:50
L5	2447	257/784.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:51
L6	25	L5 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:51
L7	1813	257/706.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:54

L8	84	L7 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul\$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:54
L9	1	((resin or mold or encapsul\$2 or casting) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base or board) and (power or module)). clm.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:58
L10	528	(resin or mold or encapsul\$2) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base) and (power or module) and (expos\$3 or outside)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 17:00
L11	401	L10 and power and control	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 17:01
S1	1	"6201696".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 13:56
S2	1	"5940271".PN.	USPAT; USOCR	OR	ON	2009/08/04 13:56
S3	1	"5398160".PN.	USPAT; USOCR	OR	ON	2009/08/04 13:57
S4	1	"5398160".PN.	USPAT; USOCR	OR	ON	2009/08/04 14:05
S5	1	"5386342".PN.	USPAT; USOCR	OR	ON	2009/08/04 14:05
S6	1	"4814943".PN.	USPAT; USOCR	OR	ON	2009/08/04 14:05
S7	2616	257/723.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05

S8	2561	257/787.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05
S9	2447	257/784.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05
S10	1813	257/706.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05
S11	2186	257/712.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:06
S12	0	S7 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:07
S14	43	S8 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:07
S17	65	S11 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:08
S18	1	S14 and modulus and hardness and (expansion or coeffecient)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:09
S19	1	"6703707".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:09

S20	1	S8 and thermoplastic and modulus and (shoreA or hardness) and (expansion or coefficient or CTE) and (kPa or GPa or kPa)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:14
S21	716	(resin or mold or encapsul\$2) and thermoplastic and modulus and (shoreA or hardness) and (expansion or coefficient or CTE) and (kPa or GPa or kPa)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:15
S22	1	S21 and flexural and shoreA	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:15
S23	1	S21 and shoreA	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:16
S24	110	S21 and shore adj A	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:16
S25	62	S21 and flexural and shore adj A	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:16
S26	413	S21 and (CTE or coefficient with expansion)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 15:16
S27	413	S26 and modulus and hardness	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 15:17
S28	413	S26 and modulus and hardness and thermoplastic	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 15:19
S29	429	257/723.ccls.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/04 16:27
S30	1791	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/04 16:28
S31	518	257/E23.119.ccls.	EPO; JPO; DERWENT	OR	ON	2009/08/04 16:28

S32	1	((resin or mold or encapsul\$2) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base) and (power or module)).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:31
S33	14	knapp.in. near2 wolfgang.in.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:33
S34	8	keser.in. near2 helmut.in.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:33
S35	19	S33 or S34	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:33
S36	0	S19 and (resin or mold or encapsul\$2) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base) and (power or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:34

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